

## 650V, 380mΩ, 11.2 A Super Junction Power MOSFET

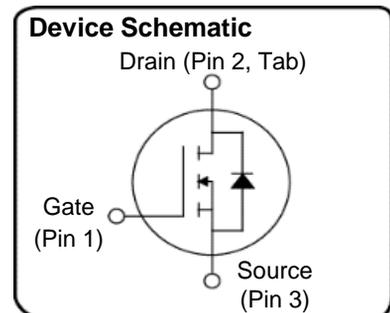
### Ordering Information

Part Number	Package Option
D3S380N65B-U	TO-220
D3S380N65E-T	TO-263
D3S380N65F-U	TO-220 FullPak (FP)



### Description

+FET™ is an advanced Super Junction Power MOSFET offering excellent efficiency through low  $R_{DS(ON)}$  and low gate charge. +FET™ is a rugged device with precision charge balance implementation designed for demanding uses such as enterprise power computing power supplies, motor control, lighting and other challenging power conversion applications.



#### Features

- LOW  $R_{DS(ON)}$
- FAST SWITCHING
- HIGH  $E_{AS}$
- REL TEST SPEC: JESD-22
- LOW OUTPUT CAPACITANCE

#### Benefits

- LOW CONDUCTION LOSSES
- HIGH EFFICIENCY
- EXCELLENT AVALANCHE PERFORMANCE

### Table 1 Key Performance Parameters

Parameters	Value	Unit
$V_{DS} @ T_J \text{ max}$	710	V
$R_{DS(on), \text{max}}$	<380	mΩ
$Q_g, \text{typ}$	16	nC
$I_D @ 25^\circ\text{C}$	11.2	A
$C_{oss}$	35	pf

#### Applications

- POWER FACTOR CORRECTION
- SERVER POWER SUPPLIES
- TELECOM POWER SUPPLIES
- INVERTERS
- MOTOR CONTROL

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@  $T_J = 25^\circ\text{C}$  ,unless otherwise specified

**Table 2 Maximum ratings**

Parameter	Symbol	Values				Unit	Note/Test Condition
		Min.	Typ.	Max.			
				220, 263 & 247	220FP		
Continuous drain current(1)	$I_D$			11.2	7.0	A	$T_C = 25^\circ\text{C}$
				7.1	4.4		$T_C = 100^\circ\text{C}$
Pulsed drain current(2)	$I_{D,pulse}$			44.7	28.0	A	$T_C = 25^\circ\text{C}$
Avalanche energy, single pulse	$E_{AS}$			202	202	mJ	$I_D=1.8\text{A}, V_{DD}=50\text{V}$
Avalanche energy, repetitive	$E_{AR}$			0.5	0.5	mJ	$I_D=1.8\text{A}, V_{DD}=50\text{V}$
Avalanche current, repetitive	$I_{AR}$			1.8	1.8	A	
MOSFET dv/dt ruggedness	dv/dt			50	50	V/ns	$V_{DS}=\dots480\text{V}$
Gate source voltage	$V_{GS}$	-30		30	30	V	static
		-30		30	30		AC (f > 1HZ)
Power dissipation for TO-220	$P_{tot}$			114	44	W	$T_C = 25^\circ\text{C}$
Operating and storage temperature	$T_J, T_{stg}$	-55		150	150	$^\circ\text{C}$	
Mounting torque				60		Ncm	M3 and M3.5 screws
					50		M3 screws
Continuous diode forward current	$I_S$			11.2	7.0	A	$T_C = 25^\circ\text{C}$
Diode pulsed current	$I_{S,pulse}$			44.7	28.0	A	$T_C = 25^\circ\text{C}$
Reverse diode dv/dt(3)	dv/dt			15	15	V/ns	$V_{DS}=\dots480\text{V}, I_{SD}<I_D$
Maximum diode commutation speed	dif/dt			500	500	A/us	$T_J = 25^\circ\text{C}$

**Table 3 Thermal characteristics**

Parameter	Symbol	Values				Unit	Note/Test Condition
		Min.	Typ.	Max.			
				220, 263 & 247	220FP		
Thermal resistance, Junction-case	$R_{thJC}$			1.3	3.1	$^\circ\text{C}/\text{W}$	
Thermal resistance, Junction-ambient	$R_{thJA}$			55.8	60	$^\circ\text{C}/\text{W}$	Leaded
Soldering temperature, wavesoldering only allowed at leads	$T_{sold}$			260	260	$^\circ\text{C}$	1.6mm form case for 10s

**Table 4 Static characteristics**

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Drain to source breakdown voltage	$V_{(BR)DSS}$	650			V	$V_{GS}=0V, I_D=1mA$
Gate threshold voltage	$V_{GS(TH)}$	2.3	3.2	4.5	V	$V_{DS}=V_{GS}, I_D=52.6\mu A$
Zero gate voltage drain current	$I_{DSS}$			1	uA	$V_{DS}=650V, V_{GS}=0V, T_J = 25^\circ C$
				40		$V_{DS}=650V, V_{GS}=0V, T_J = 150^\circ C$
Gate to source leakage current	$I_{GSS}$			100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$		320	380	mΩ	$V_{GS}=10V, I_D=5.6A, T_J = 25^\circ C$
			860		mΩ	$V_{GS}=10V, I_D=5.6A, T_J = 150^\circ C$
Gate resistance	$R_G$		1.1		Ω	Scaf-F

**Table 5 Dynamic characteristics**

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Input capacitance	$C_{iss}$		618		pF	$V_{GS}=0V, V_{DS}=100V, f=1MHz$
Output capacitance	$C_{oss}$		26.2		pF	
Reverse transfer capacitance	$C_{rss}$		4.8		pF	
Effective output capacitance, energy related 1	$C_{o(er)}$		63		pF	$V_{DS}=0\dots 480V, V_{GS}= 0V$
Effective output capacitance, time related 2	$C_{o(tr)}$		137		pF	$I_D=constant, V_{DS}=0\dots 480V, V_{GS}= 0V$
Turn on delay time	$t_{d(on)}$		5		ns	$V_{DD}=400V, I_D=5.6A, R_G=1.0\Omega, V_{GS}=10V$
Rising time	$t_r$		21		ns	
Turn off delay time	$t_{d(off)}$		20		ns	
Fall time	$t_f$		24		ns	

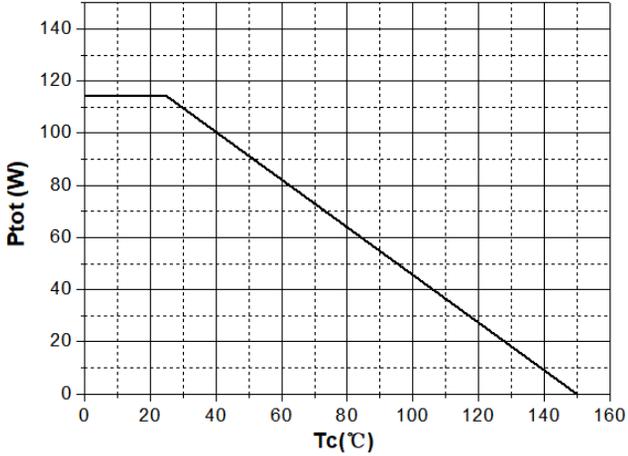
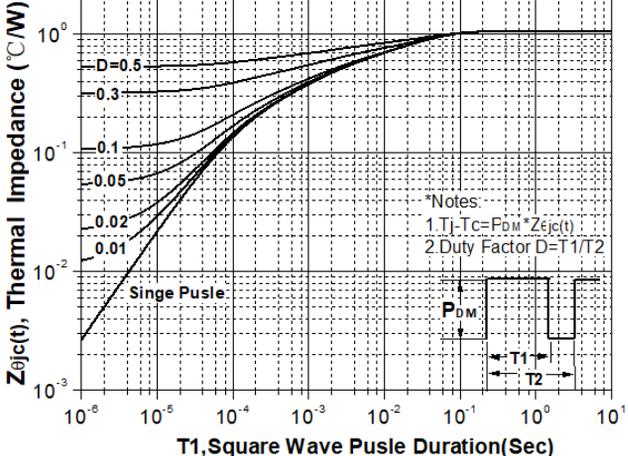
**Table 6 Gate charge characteristics**

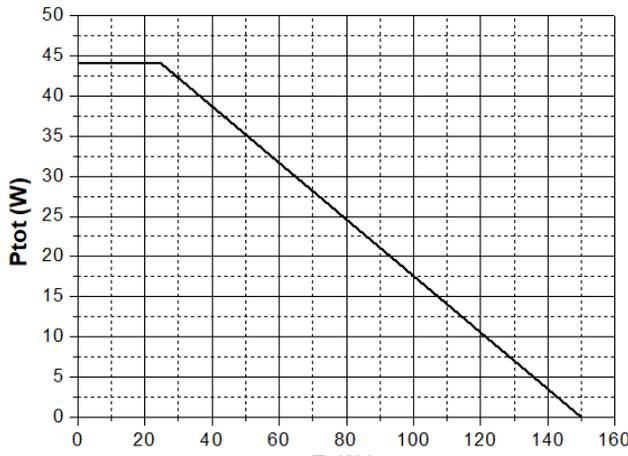
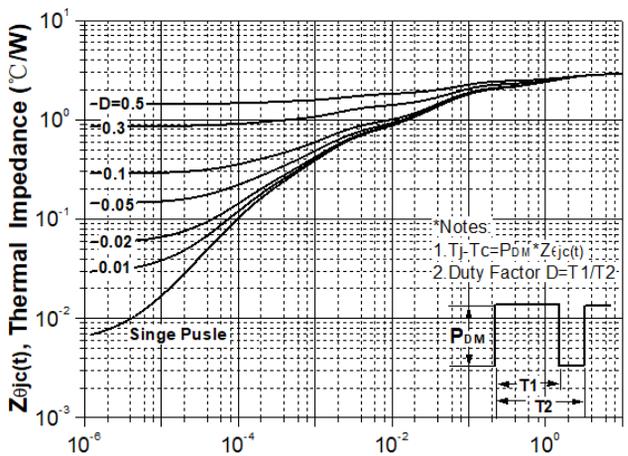
Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Total gate charge	$Q_g$		15.4		nC	$V_{DD}=480V, V_{GS}=0 \text{ to } 10V, I_D=5.6A$
Gate-source charge	$Q_{gs}$		4.1		nC	
Gate-drain charge	$Q_{gd}$		6.2		nC	
Gate plateau voltage	$V_{plateau}$		5.0		V	

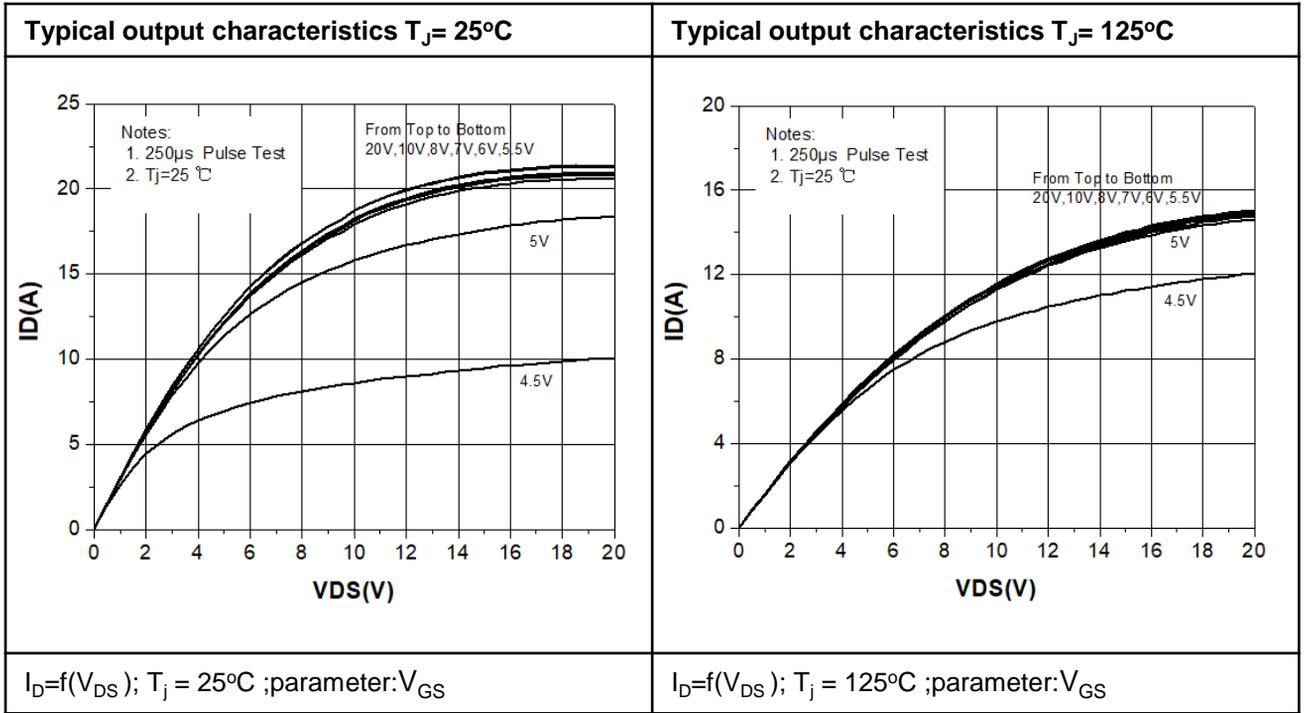
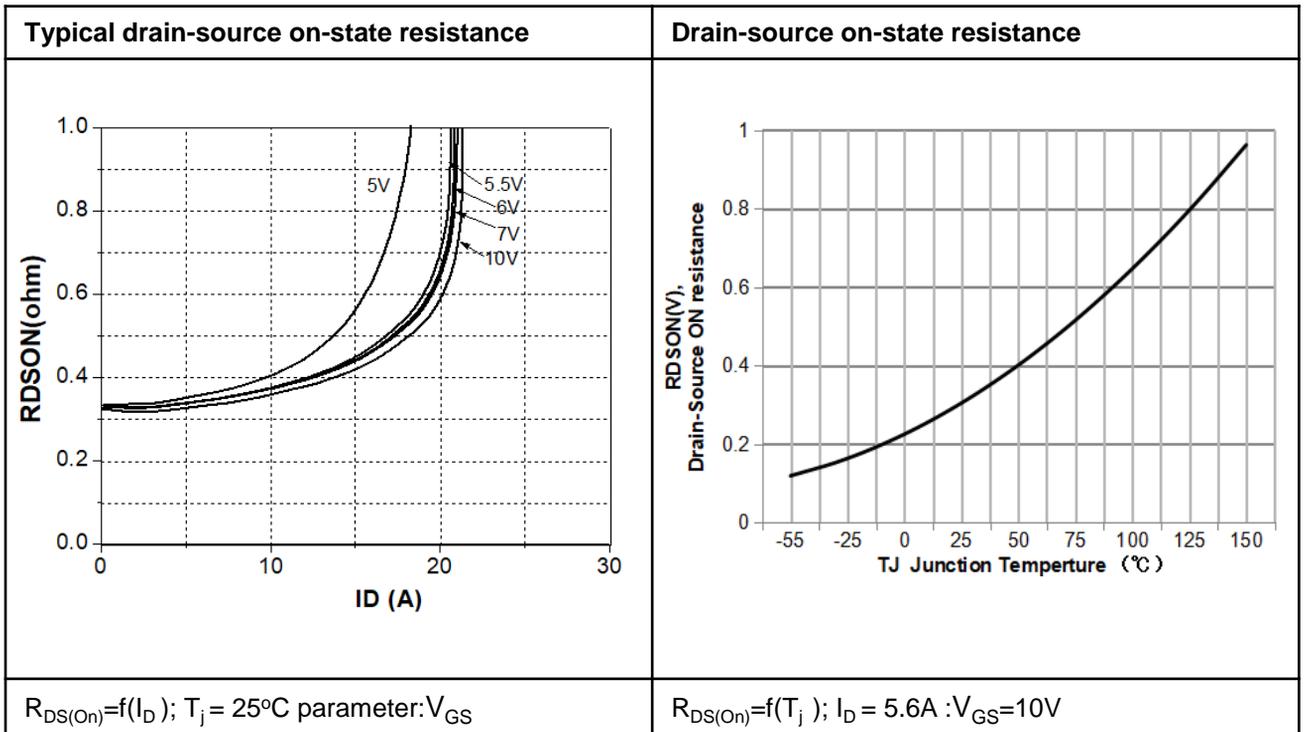
**Table 7 Reverse diode characteristics**

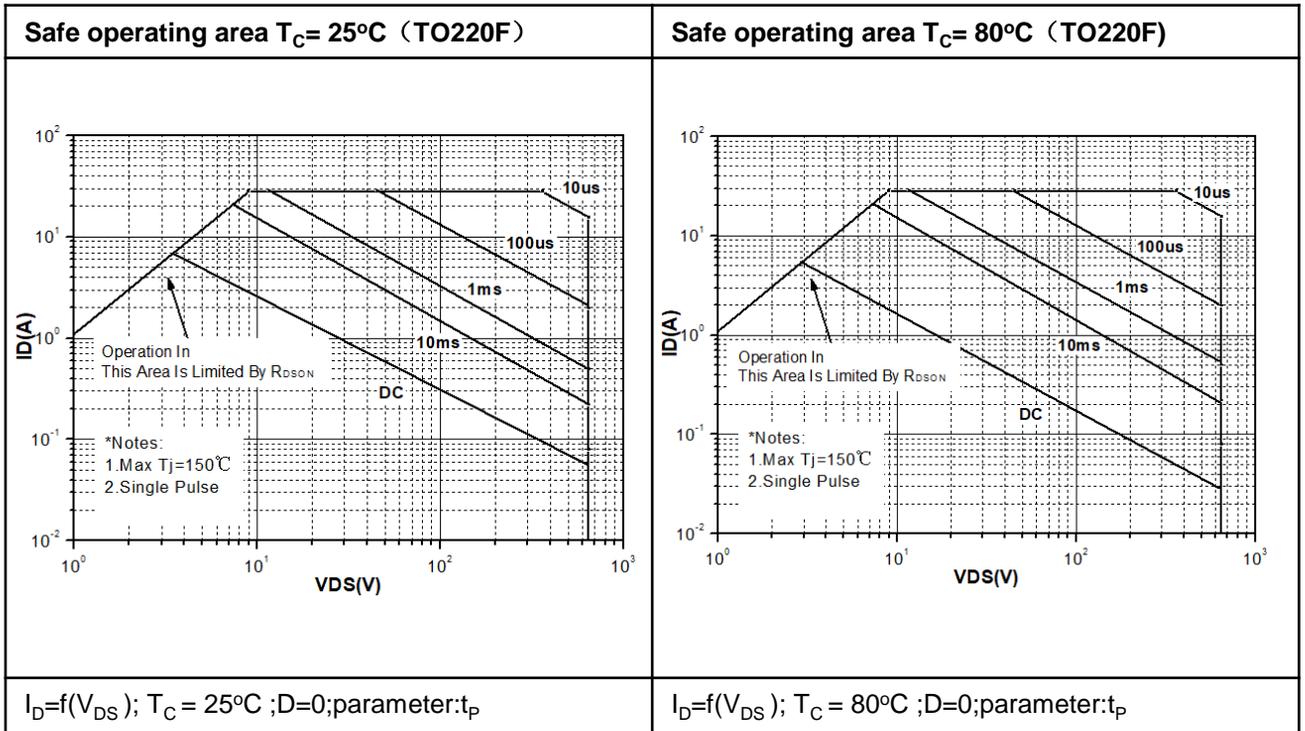
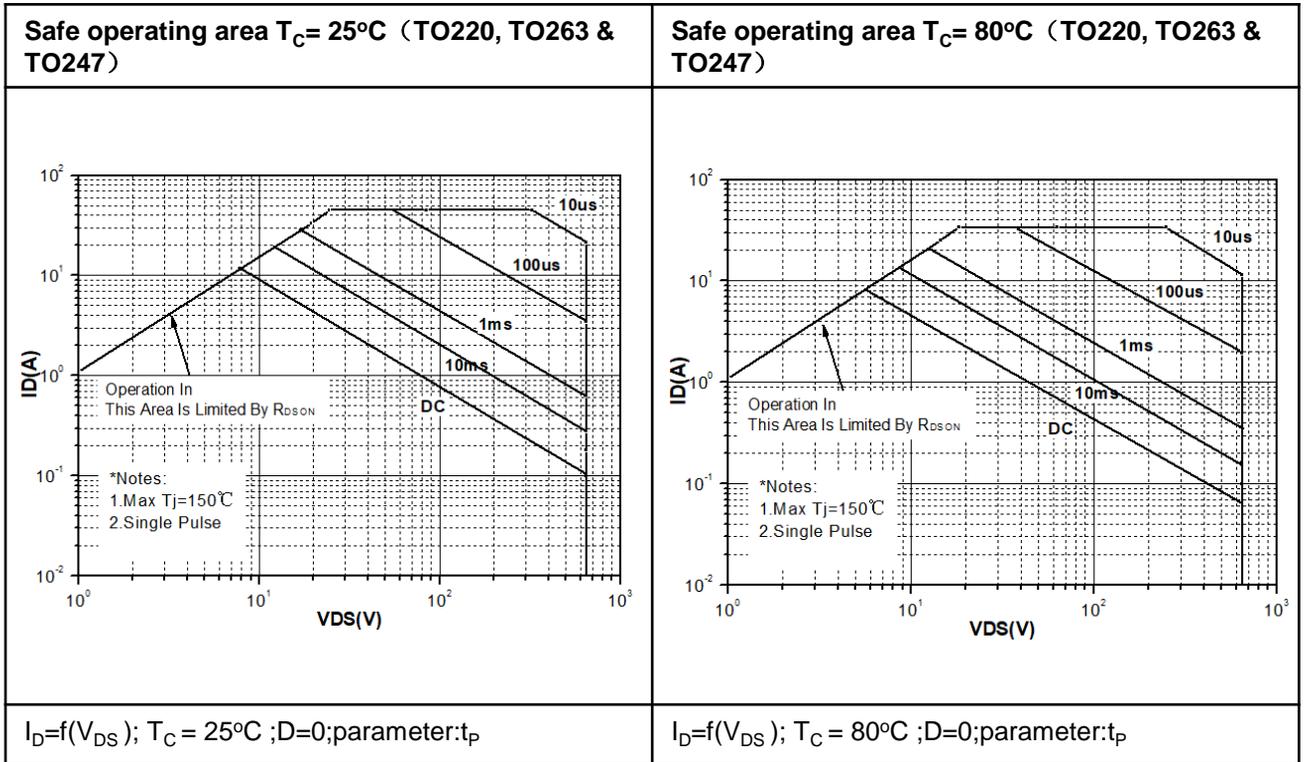
Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	$V_{SD}$		0.84	0.96	V	$I_F=11.2A, V_{GS}=0V, T_J = 25^\circ C$
Reverse recovery time	$t_{rr}$		232		ns	$I_F=11.2A, dI_F/dt=100A/us$
Reverse recovery charge	$Q_{rr}$		2.0		uC	
Peak reverse recovery current	$I_{rrm}$		16.6		A	

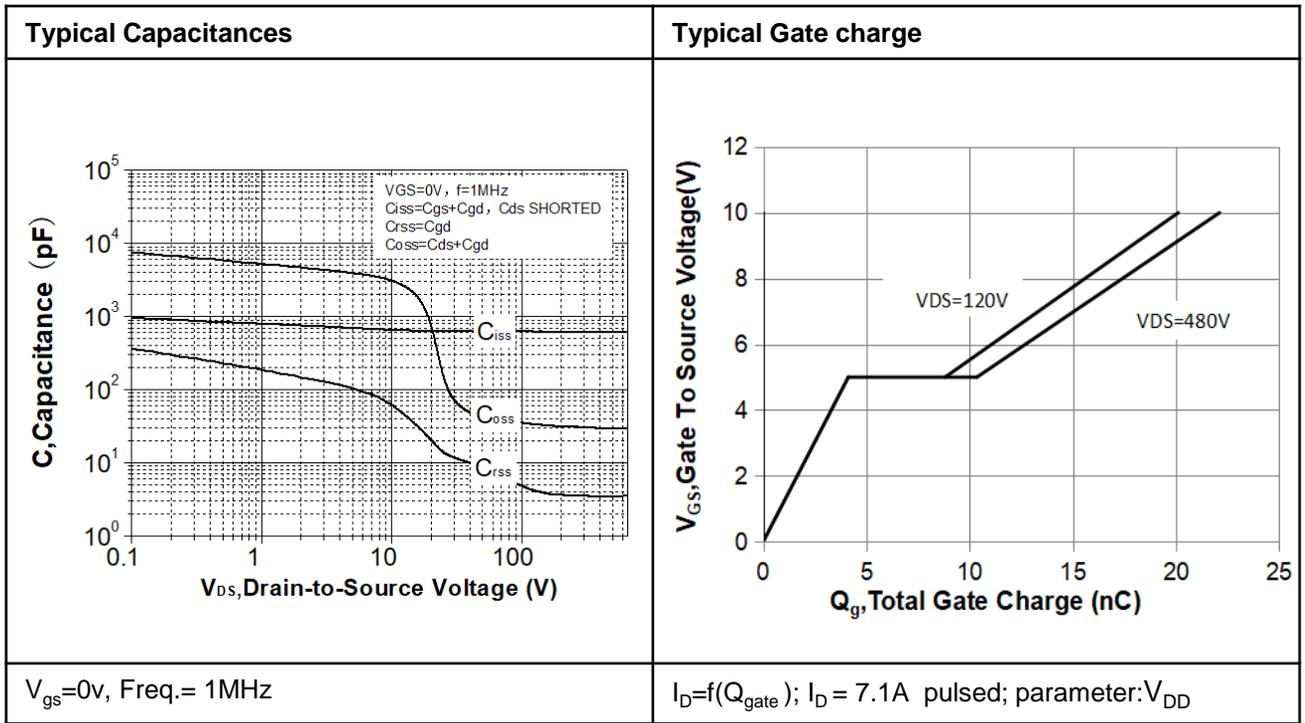
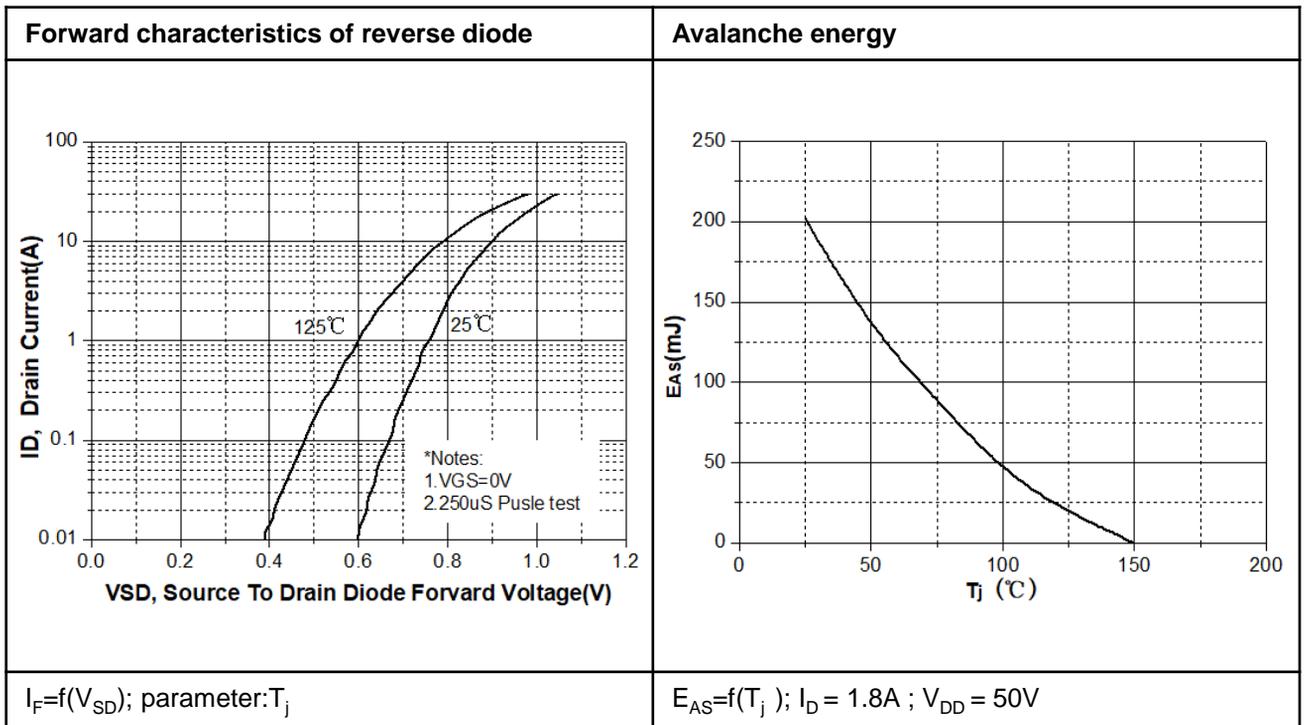
**Table 8 Thermal Performance**

Power dissipation (TO220, TO263 & TO247)	Max. transient thermal impedance (TO220, TO263 & TO247)
	 <p>*Notes: 1. <math>T_J - T_C = P_{DM} * Z_{thJC}(t)</math> 2. Duty Factor <math>D = T1/T2</math></p>
<p><math>P_{tot} = f(T_C)</math></p>	<p><math>Z_{thJC} = f(t_p)</math>; parameter: <math>D = t_p/T</math></p>

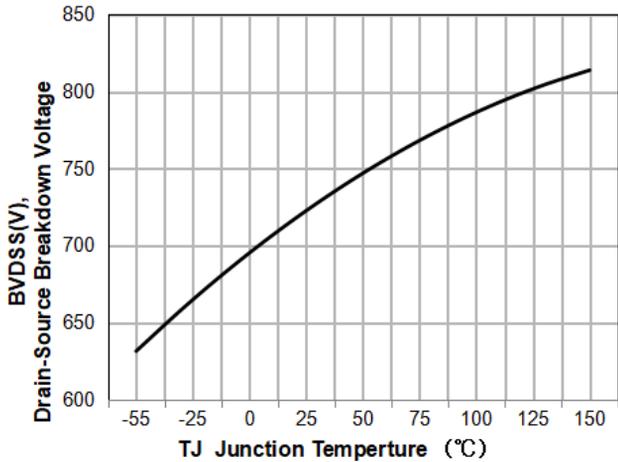
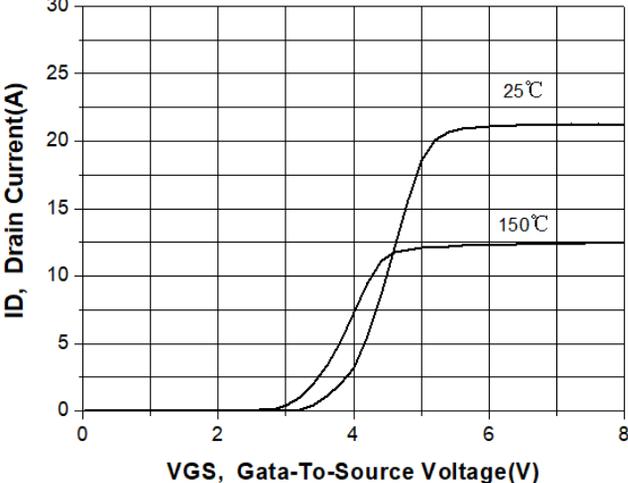
Power dissipation (TO220F)	Max. transient thermal impedance (TO220F)
	 <p>*Notes: 1. <math>T_J - T_C = P_{DM} * Z_{thJC}(t)</math> 2. Duty Factor <math>D = T1/T2</math></p>
<p><math>P_{tot} = f(T_C)</math></p>	<p><math>Z_{thJC} = f(t_p)</math>; parameter: <math>D = t_p/T</math></p>

**Table 9 Output Characteristics**

**Table 10 Drain Source Resistance**


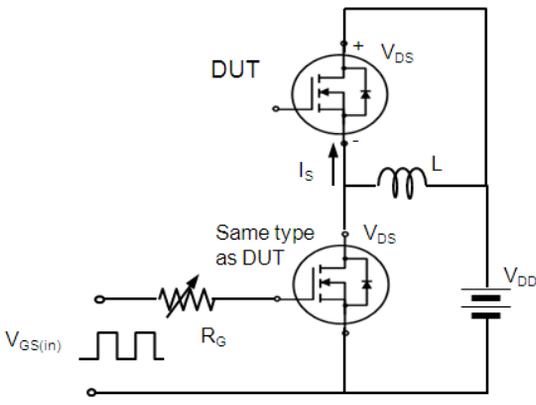
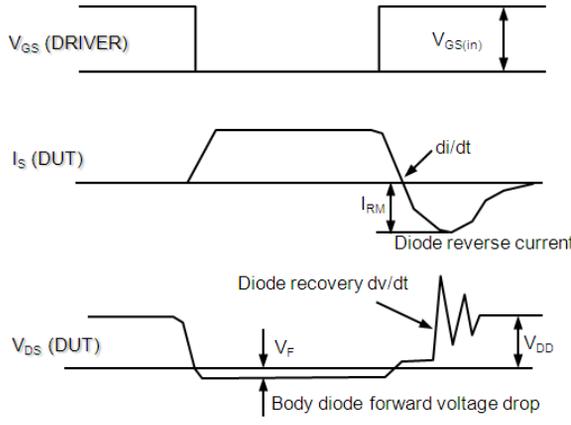
**Table 12 Safe Operating Area**


**Table 12 Capacitances and Gate Charge**

**Table 13 Diode Characteristics and Avalanche Energy**


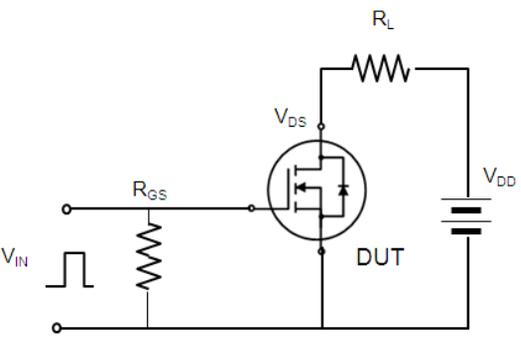
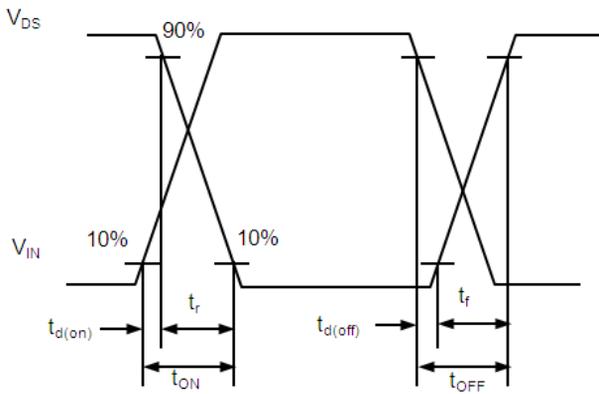
**Table 16 Breakdown Voltage and Transfer Characteristics**

Drain-source breakdown voltage	Transfer Characteristics
 <p>The graph shows the Drain-Source Breakdown Voltage (BVDSS) in Volts (V) on the y-axis (ranging from 600 to 850) versus the TJ Junction Temperature in degrees Celsius (°C) on the x-axis (ranging from -55 to 150). The curve shows a positive correlation, starting at approximately 630V at -55°C and rising to about 815V at 150°C.</p>	 <p>The graph shows the Drain Current (ID) in Amperes (A) on the y-axis (ranging from 0 to 30) versus the Gate-To-Source Voltage (VGS) in Volts (V) on the x-axis (ranging from 0 to 8). Two curves are shown for different temperatures: 25°C and 150°C. The 25°C curve shows a higher drain current, reaching a saturation point of approximately 21A at 6V VGS. The 150°C curve shows a lower drain current, reaching a saturation point of approximately 12.5A at 6V VGS.</p>
$V_{BR(DSS)} = f(T_j); I_D = 0.25mA$	$I_D = f(V_{GS});  V_{DS}  > 2 I_D R_{DS(On)max}; parameter: T_j$

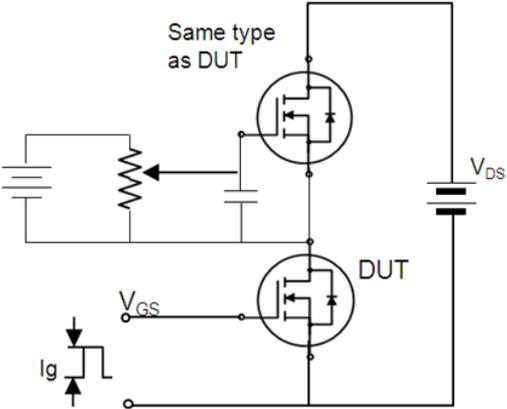
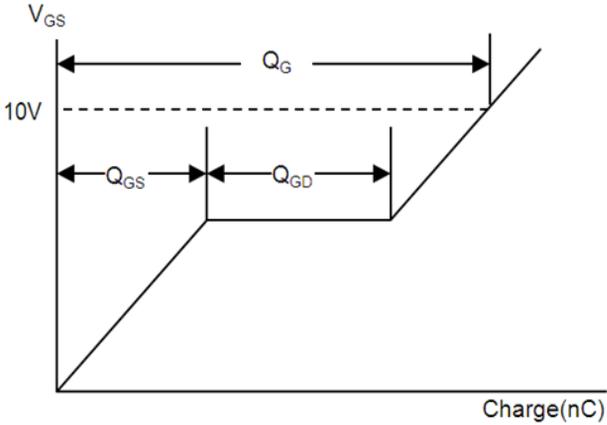
**Table 15 Diode Recovery Characteristic**

Test Circuit For Diode Recovery	Test Waveform For Diode Recovery
 <p>*. <math>dv/dt</math> controlled by <math>R_G</math>          *. <math>I_S</math> controlled by pulse period</p>	

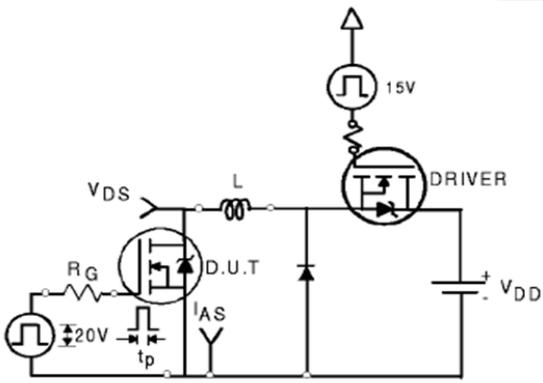
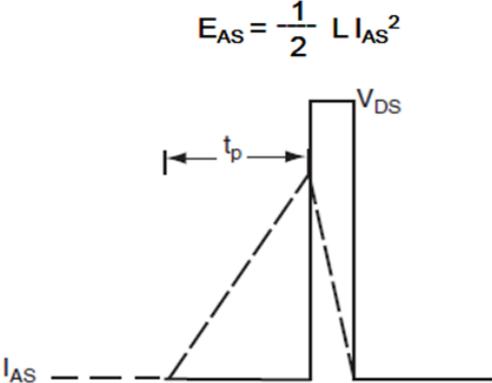
**Table 16 Switching Time Characteristic**

Test Circuit for Switching Time	Test Waveform for Switching Time
	

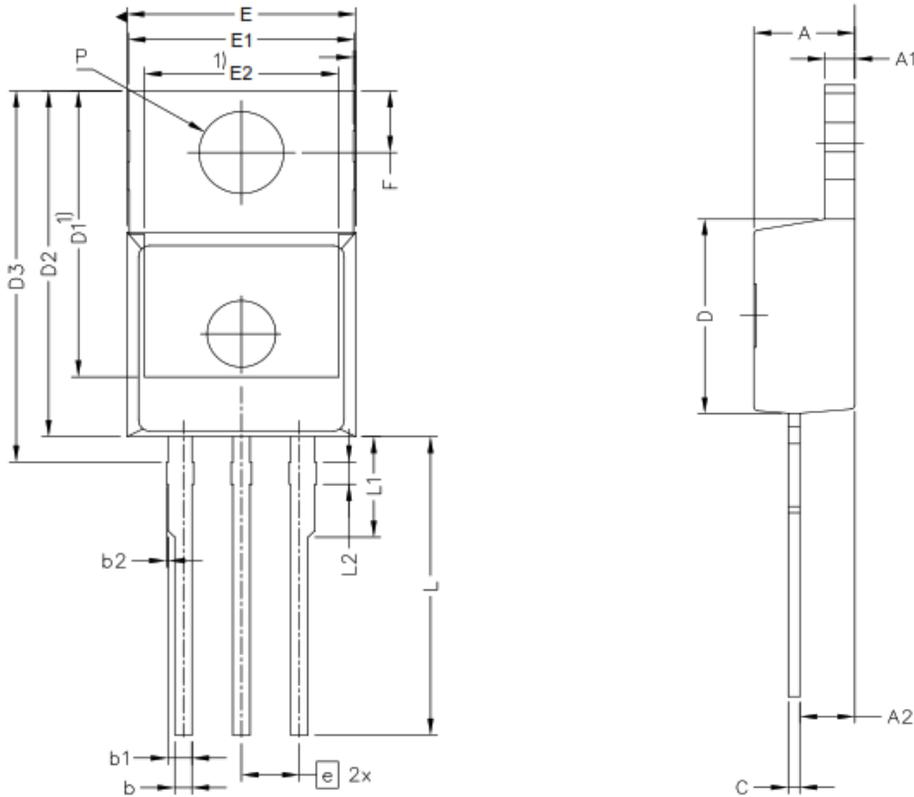
**Table 17 Gate Charge Characteristic**

Test Circuit For Gate Charge	Test Waveform For Gate Charge
	

**Table 18 Unclamped Inductive Characteristic**

Test Circuit For Unclamped Inductive	Test Waveform For Unclamped Inductive
	 $E_{AS} = \frac{1}{2} L I_{AS}^2$

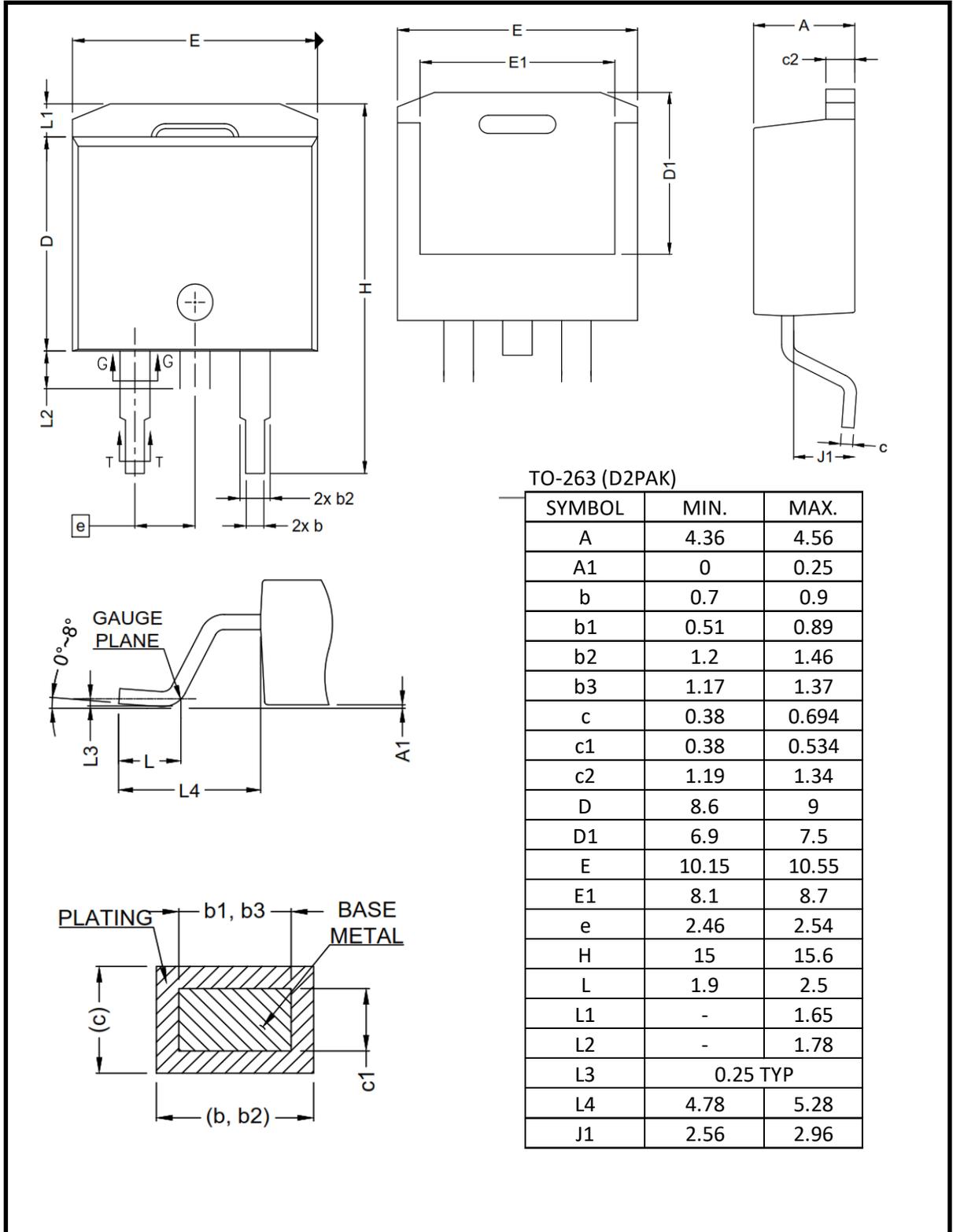
**4a) TO-220**



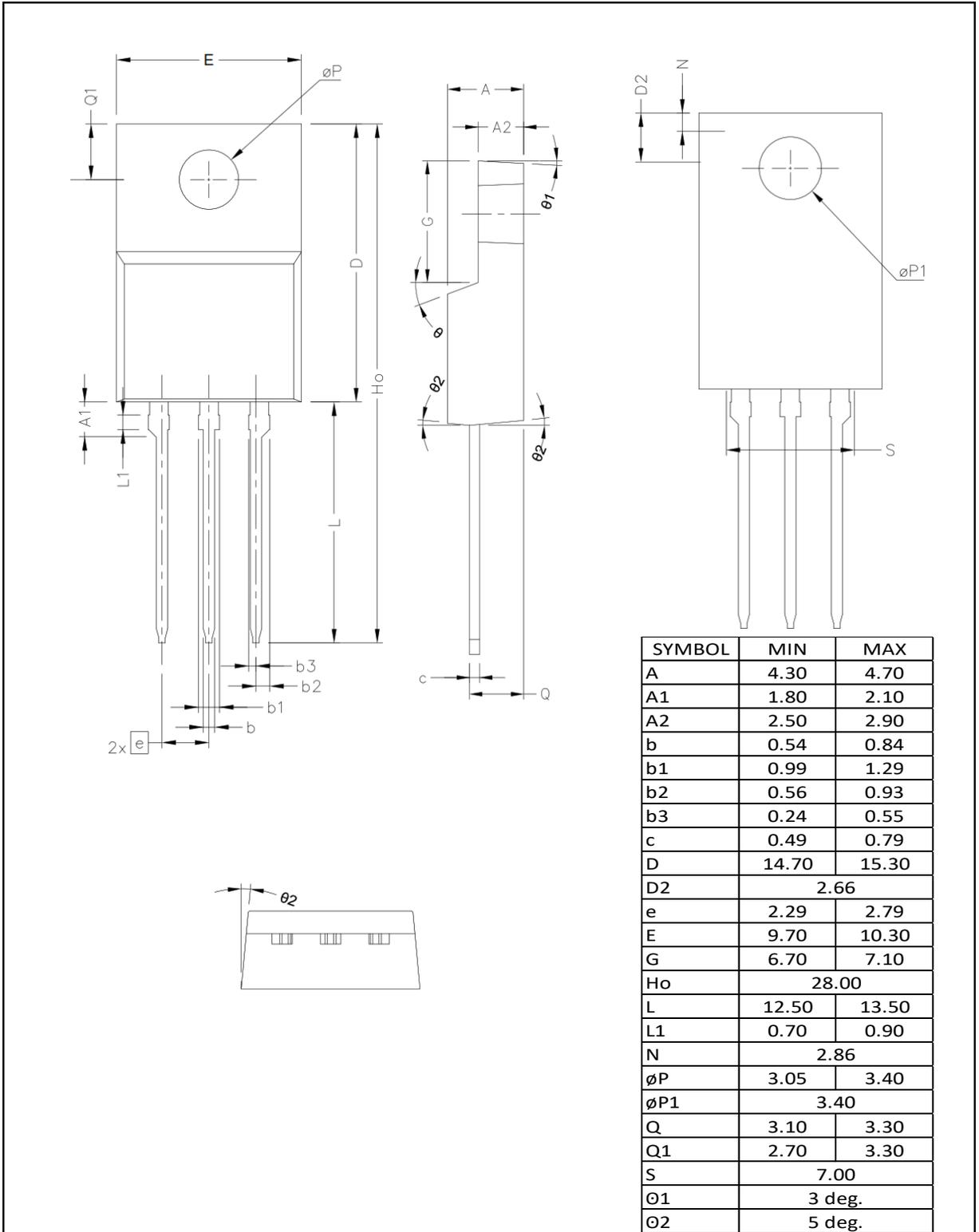
TO-220 3L

SYMBOL	MIN	MAX
A	4.20	4.60
A1	1.20	1.40
A2	2.20	2.60
b	0.65	0.85
b1	0.95	1.15
b2		0.15
C	0.40	0.60
D	9.05	9.45
D1	12.95	
D2	15.35	15.95
D3	16.50	17.10
E	9.80	10.20
E1	9.70	10.10
E2	8.50	
e	2.46	2.54
F	2.60	3.00
L	13.00	14.00
L1	4.35	4.75
L2	0.90	1.10
P	3.55	3.85

4b) TO-263



**4C) TO-220 FullPak**



## Revision History

Revision	Release Date	Comments
1.0	1-Dec 2017	Preliminary Datasheet Draft
2.0	2-Jan 2019	Characterization and enhancements

## Resources

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